Title:       Adding CD-PR as additional wafer probe site         Customer Contact:       PCN Manager       Dept:       Quality Services         Proposed 1 <sup>st</sup> Ship Date:       Jan 9, 2022       Estimated Sample Availability:       Samples not supported         Change Type:       Assembly Process       Assembly Materials         Design       Electrical Specification       Mechanical Specification         ☑ Test Site       Packing/Shipping/Labeling       Test Process         ☑ Wafer Bump Site       Wafer Bump Material       Wafer Bump Process			
Proposed 1 <sup>st</sup> Ship Date:  Jan 9, 2022  Estimated Sample Availability:  Samples not supported  Change Type:  Assembly Site  Assembly Process  Design  Electrical Specification  Test Site  Packing/Shipping/Labeling  Wafer Bump Site  Wafer Bump Material  Wafer Bump Process			
Proposed 1st Ship Date:       Jan 9, 2022       Availability:       supported         Change Type:       □       Assembly Process       □       Assembly Materials         □       Design       □       Electrical Specification       □       Mechanical Specification         □       Test Site       □       Packing/Shipping/Labeling       □       Test Process         □       Wafer Bump Site       □       Wafer Bump Material       □       Wafer Bump Process			
□ Assembly Site       □ Assembly Process       □ Assembly Materials         □ Design       □ Electrical Specification       □ Mechanical Specification         □ Test Site       □ Packing/Shipping/Labeling       □ Test Process         □ Wafer Bump Site       □ Wafer Bump Material       □ Wafer Bump Process			
□ Design       □ Electrical Specification       □ Mechanical Specification         □ Test Site       □ Packing/Shipping/Labeling       □ Test Process         □ Wafer Bump Site       □ Wafer Bump Material       □ Wafer Bump Process			
✓ Test Site       ☐ Packing/Shipping/Labeling       ☐ Test Process         ☐ Wafer Bump Site       ☐ Wafer Bump Material       ☐ Wafer Bump Process			
☐ Wafer Bump Site ☐ Wafer Bump Material ☐ Wafer Bump Process	n		
☐ Wafer Fab Site ☐ Wafer Fab Materials ☐ Wafer Fab Process			
Part number change			
PCN Details			
Description of Change:			
Iisted in the "Product Affected" Section. See table below for change details.  Current:  New:  EWS Test Site  TI Melaka (TIEM-PR)  Ti Chengdu (CD-PR)  Test coverage, insertions, conditions will remain consistent with current testing.			
Reason for Change:			
Enable additional probe capacity to support high volume ramps.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
None.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
	1		
TPL5010QDDCRQ1 TPL5110QDDCTQ1 LMR16006YQ5DDCRQ1 LMR16006YQDDCTQ			
TPL5010QDDCRQ1         TPL5110QDDCTQ1         LMR16006YQ5DDCRQ1         LMR16006YQDDCTQ1           TPL5010QDDCTQ1         LMR16006YQ3DDCRQ1         LMR16006YQ5DDCTQ1         LMR16006YQ5DDCTQ1			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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